

## Capacitor Materials

### ET1801



#### Lead Free Solderable End Termination

##### Description:

ET1801 is a Pb and Cd free solderable Ag/Pd/Pt end termination designed for use on MLCC (multilayer ceramic chip capacitors). It offers excellent solderability and leach resistance.

##### ● Key Benefits :

- Lead and Cadmium free
- Suitable rheology for machine dip application
- Excellent Solderability and leach resistance
- Compatible on titanate ceramic bodies

##### ● Typical Properties:

###### Viscosity :

30-40 Kcps, Brookfield RVT,  
SC4-14 spindle and 6R cup at 10 RPM and 25°C.

###### Solids :

79.25 ± 1.0%

###### Solderability :

60Sn/40Pb @ 245°C  
5 sec dip, RMA Flux  
≥ 95% Solder Coverage

###### Solder Leaching :

60Sn/40Pb @ 245°C  
20 sec dip, RMA Flux  
≥ 95% Solder Coverage

##### ● Recommended Processing Guidelines:

###### Drying :

180°C peak drying profile  
10 minutes at peak temperature  
20 minute total cycle time

###### Firing Profile :

Fire at 780-810°C  
Dwell time of 5-6 minutes

###### Thinner :

RV-372 (Terpineol)

###### Warranty:

Material guaranteed to meet specifications  
for 6 months from date of shipment.

###### Storage :

Store in a dry location at 5-25°C.  
**DO NOT REFRIGERATE.**  
Allow paste to come to room temperature  
prior to opening.  
Spatulate well before using.

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The descriptions and engineering data shown here have been compiled by Heraeus using commonly-accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for a particular application.

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